

Product/Process Change Notification



N° 2019-162-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting TLE941*

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-06-14.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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Products affected

Please refer to attached affected product list 1_cip19162_A

Detailed change information

Subject: Several changes affecting TLE941*

Reason/Motivation: To secure the future use of TLE941* with optimized die and package, combined with improved MSL level from 3 to 2a. The expansion of the final test location and plating subcontractor will assure continuity of supply enabling flexible manufacturing.

Description

Old

New

ANY: Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.

Sales code:
TLE941xyEL

Sales code:
TLE941xyES

DATA SHEET: Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification

Data sheet:
TLE941xyEL

Data sheet:
TLE941xyES

PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)

Wafer backside metallization:
Si

Wafer backside metallization:
NiAg-System

PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)

Wafer frontside pad metallization:
Cu/NiMoP/Pd/Au

Wafer frontside pad metallization:
Cu

PROCESS - ASSEMBLY: Change in critical dimensions of package

Package (Thickness):
PG-SSOP-24 (1,47mm)

Package (Thickness):
PG-TSDSO-24 (0,95mm)

PROCESS - ASSEMBLY: Change in leadframe dimensions

Leadframe Exposed Pad:
6,4 x 2,65mm

Leadframe Exposed Pad:
6,4 x 2,77mm

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PROCESS - ASSEMBLY: Die attach material	Die attach glue: AB3230	Die attach glue: TS333
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	Mold Compound: CEL9220	Mold Compound: G700
PROCESS - ASSEMBLY: Change of product marking	Product marking: TLE941xyEL	Product marking: TLE941xyES
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site.	Plating subcontractor: SII Ishizaki (Melaka) Sdn Bhd	Plating subcontractor: SII Ishizaki (Melaka) Sdn Bhd AND Syntronixs (Melaka) Asia Sdn Bhd
PACKING/SHIPPING: Dry pack requirements change	Dry pack: MSL3	Dry pack: MSL2a
EQUIPMENT: Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	Production equipment line: PG-SSOP-24	Production equipment line: PG-TSDSO-24
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Final test location: Infineon Technologies Asia Pacific Pte. Ltd., Singapore, Singapore	Final test location: Infineon Technologies Asia Pacific Pte. Ltd., Singapore, Singapore AND Infineon Technologies Batam P.T., Batam, Indonesia
SP number	see 5_cip19162	
Parts per reel	2,5k parts per reel	3k parts per reel

Product identification

SP number and ordering part number are different.

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Anticipated impact of change

Based on the final test location verification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in function expected.

DeQuMa-ID(s): SEM-AN-02 / SEM-DS-01 / SEM-PW-06 / SEM-PW-07 / SEM-PA-01 / SEM-PA-03 / SEM-PA-07 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-PS-02 / SEM-EQ-01 / SEM-TF-01

Attachments

1_cip19162_A	affected product list
4_cip19162_A	new data sheets
5_cip19162_A	replacement table (SP number)

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2021-11-05
Last order date (LOD) [2]	2021-11-05
Last delivery date (LDD) [3]	2022-11-07

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.

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Sales name	SP number	OPN	Package
TLE94108EL	SP001209006	TLE94108ELXUMA1	PG-SSOP-24
TLE94110EL	SP001209008	TLE94110ELXUMA1	PG-SSOP-24
TLE94112EL	SP001209010	TLE94112ELXUMA1	PG-SSOP-24